



ALPHA & OMEGA
SEMICONDUCTOR

AOSP21357

30V P-Channel MOSFET

General Description

- Latest advanced trench technology
- Low $R_{DS(ON)}$
- High Current capability
- RoHS and Halogen-Free Compliant

Product Summary

V_{DS}	-30V
I_D (at $V_{GS}=-10V$)	-16A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	< 8.5mΩ
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	< 13mΩ

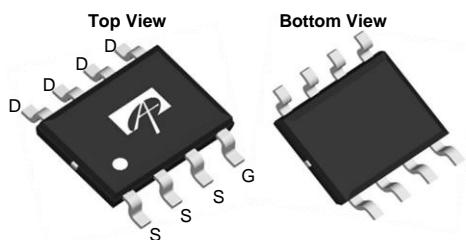
Applications

- Notebook AC-in load switch
- Battery protection charge/discharge

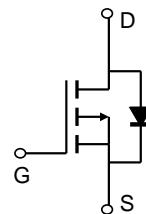
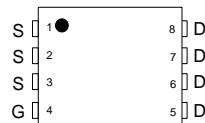
100% UIS Tested
100% R_g Tested



SO-8



Top View



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOSP21357	SO-8	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 25	V
Continuous Drain Current	I_D	-16	A
$T_A=70^\circ\text{C}$		-12.5	
Pulsed Drain Current ^C	I_{DM}	-64	
Avalanche Current ^C	I_{AS}	39	A
Avalanche energy $L=0.1\text{mH}$ ^C	E_{AS}	76	mJ
Power Dissipation ^B	P_D	3.1	W
$T_A=25^\circ\text{C}$		2.0	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10\text{s}$	$R_{\theta JA}$	31	40	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		59	75	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	16	24	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
advanced	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm25\text{V}$			±100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.3	-1.75	-2.3	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-16\text{A}$ $T_J=125^\circ\text{C}$		7 9.6	8.5 11.6	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-12\text{A}$		10.5	13	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-16\text{A}$		50		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.7	-1	V
I_S	Maximum Body-Diode Continuous Current				-4	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		2830		pF
C_{oss}	Output Capacitance			430		pF
C_{rss}	Reverse Transfer Capacitance			365		pF
R_g	Gate resistance	$f=1\text{MHz}$		14	28	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-16\text{A}$		50	70	nC
$Q_g(4.5\text{V})$	Total Gate Charge			25	35	nC
Q_{gs}	Gate Source Charge			9		nC
Q_{gd}	Gate Drain Charge			12		nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=0.95\Omega, R_{\text{GEN}}=3\Omega$		12		ns
t_r	Turn-On Rise Time			12.5		ns
$t_{D(\text{off})}$	Turn-Off Delay Time			135		ns
t_f	Turn-Off Fall Time			63		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-16\text{A}, di/dt=500\text{A}/\mu\text{s}$		32		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-16\text{A}, di/dt=500\text{A}/\mu\text{s}$		62		nC

A. The value of R_{JJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.

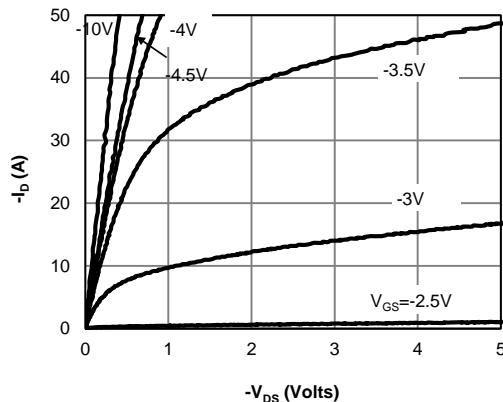
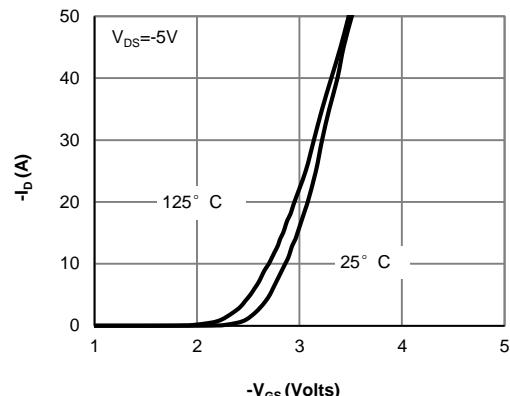
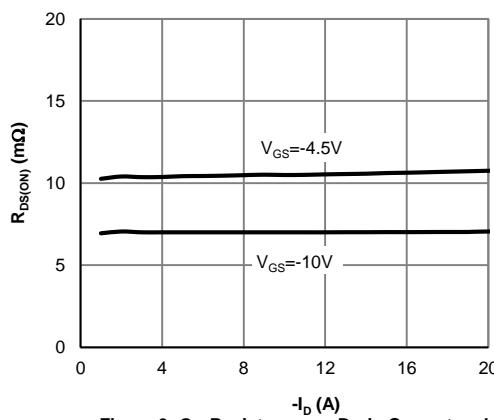
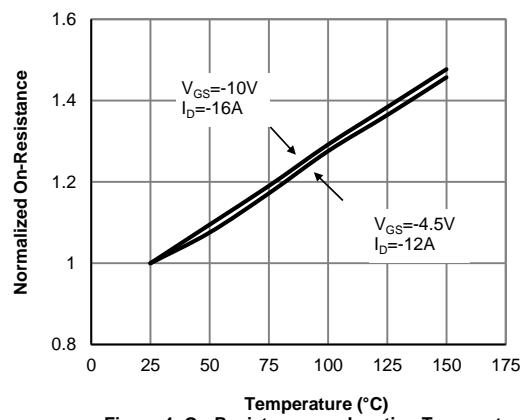
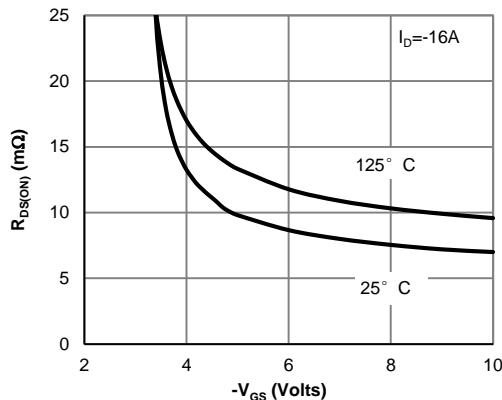
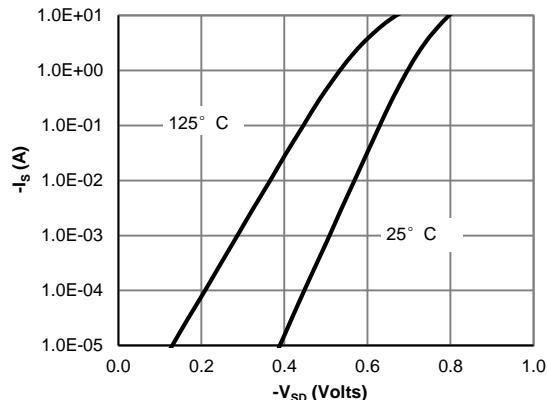
C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

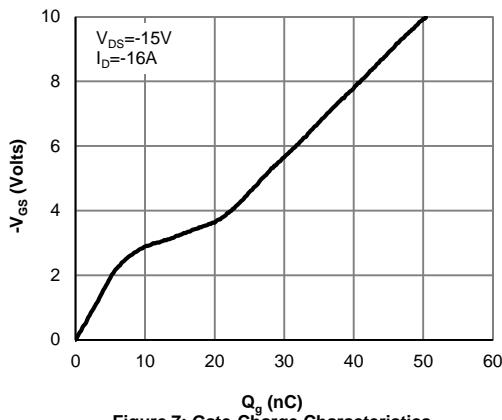
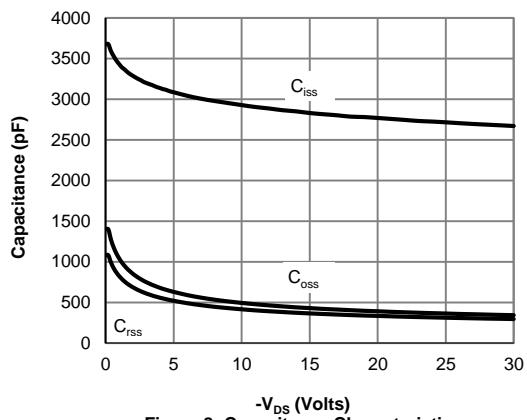
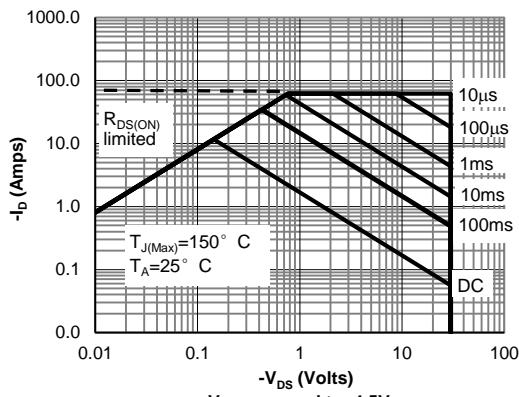
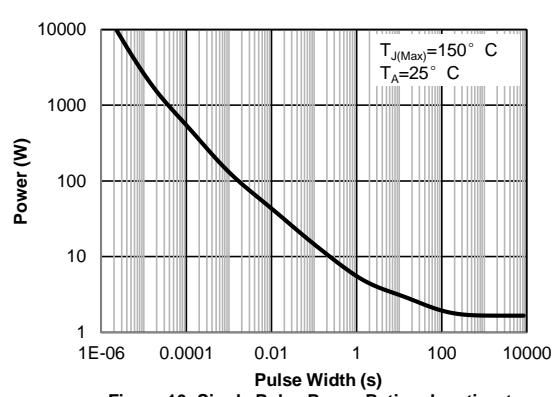
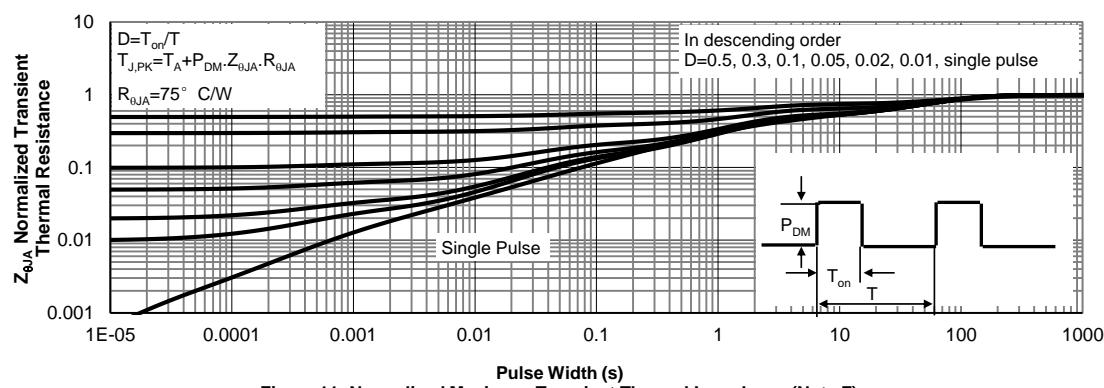
D. The R_{JJA} is the sum of the thermal impedance from junction to lead $R_{J\text{L}}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.

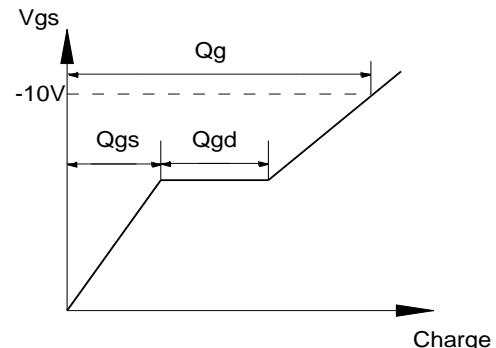
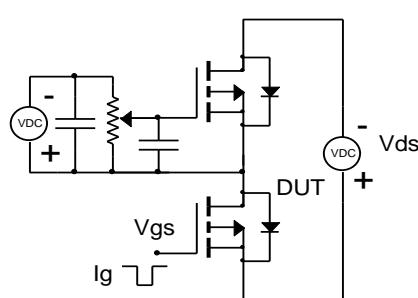
F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

APPLICATIONS OR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN, FUNCTIONS AND RELIABILITY WITHOUT NOTICE.

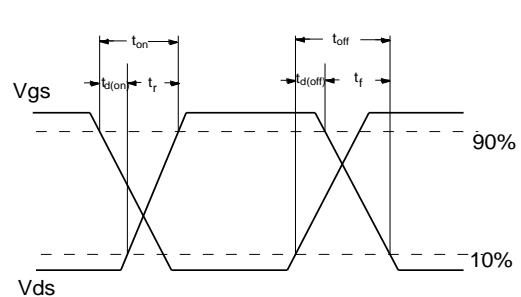
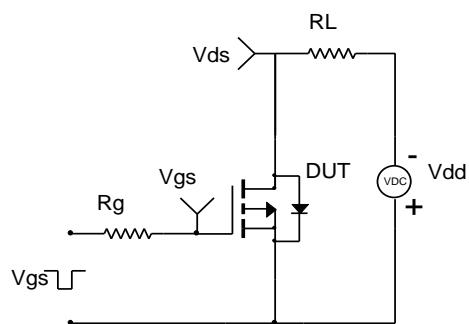
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

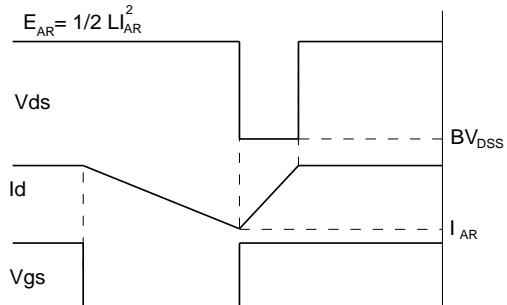
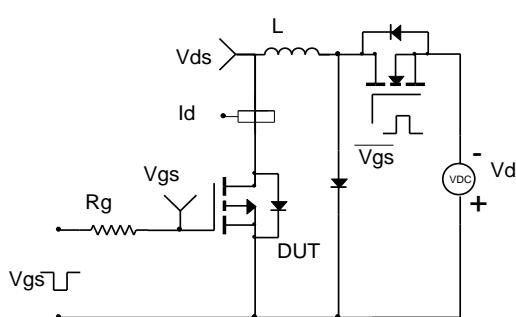
Gate Charge Test Circuit & Waveform



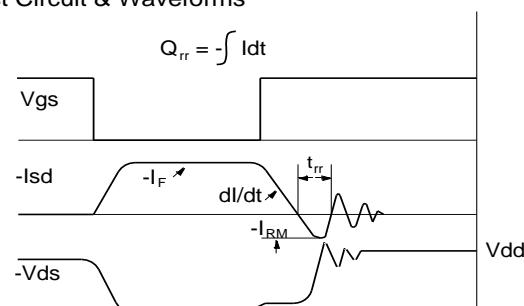
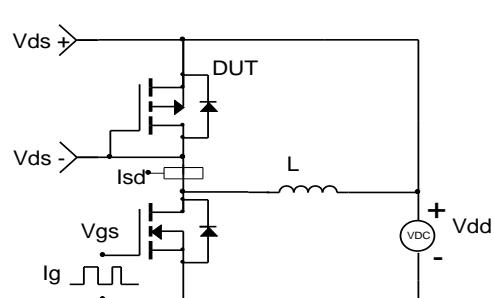
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Alpha & Omega manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [NTNS3A92PZT5G](#) [IRFD120](#) [IRFF430](#) [JANTX2N5237](#) [2N7000](#)
[AOD464](#) [2SK2267\(Q\)](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [SSM6J414TU,LF\(T](#) [751625C](#)
[IPS70R2K0CEAKMA1](#) [BSF024N03LT3 G](#) [PSMN4R2-30MLD](#) [TK31J60W5,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#) [DMN1017UCP3-7](#)
[EFC2J004NUZTDG](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE2384](#) [NTE2969](#) [NTE6400A](#) [DMC2700UDMQ-7](#)
[DMN2080UCB4-7](#) [DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [SSM6P54TU,LF](#) [DMP22D4UFO-7B](#) [IPS60R3K4CEAKMA1](#)
[DMN1006UCA6-7](#) [DMN16M9UCA6-7](#) [STF5N65M6](#) [IRF40H233XTMA1](#) [IPSA70R950CEAKMA1](#) [IPSA70R2K0CEAKMA1](#) [STU5N65M6](#)
[C3M0021120D](#)